

(Preliminary) PL123E-09

PIN DESCRIPTIONS

Nama	Packag	е Туре	Turne	Description	
Name	TSSOP-16L	SOP-16L	Туре	Description	
	1	1	I	Input reference frequency.	
CLKA1 ^[2]	2	2	0	Buffered clock output, Bank A	
CLKA2 ^[2]	3	3	0	Buffered clock output, Bank A	
VDD	4,13	4,13	Р	VDD connection	
GND	5,12	5,12	Р	GND connection	
CLKB1 ^[2]	6	6	0	Buffered clock output, Bank B	
CLKB2 ^[2]	7	7	0	Buffered clock output, Bank B	
S2 ^[3]	8	8	I	Selector input	
S1 ^[3]	9	9	I	Selector input	
CLKB3 ^[2]	10	10	0	Buffered clock output, Bank B	
CLKB4 ^[2]	11	11	0	Buffered clock output, Bank B	
CLKA3 ^[2]	14	14	0	Buffered clock output, Bank A	
CLKA4 ^[2]	15	15	0	Buffered clock output, Bank A	
CLKOUT ^[2]	16	16	0	Buffered clock output. Internal feedback on this pin.	

Notes: 1: Weak pull-down. 2: Weak pull-down on all outputs. 3: Weak Pull-Up on S1 and S2

SELECTOR DEFINITION

S2	S1	CLOCK A1–A4 (Bank A)	CLOCK B1–B4 (Bank B)	CLKOUT	Output Source	PLL Shutdown
0	0	Three-state	Three-state	Driven	PLL	Ν
0	1	Driven	Three-state	Driven	PLL	Ν
1	0	Driven	Driven	Driven	Reference	Y
1	1	Driven	Driven	Driven	PLL	Ν

INPUT / OUTPUT SKEW CONTROL

The PL123E-09 will achieve Zero Delay from input to output when all the outputs are loaded equally. Adjustments to the input/output delay can be made by adding additional loading to the CLKOUT pin. Please contact Micrel for more information.



LAYOUT RECOMMENDATIONS

The following guidelines are to assist you with a performance optimized PCB design:

Signal Integrity and Termination Considerations

- Keep traces short!
- Trace = Inductor. With a capacitive load this equals ringing!
- Long trace = Transmission Line. Without proper termination this will cause reflections (looks like ringing).
- Design long traces as "striplines" or "microstrips" with defined impedance.
- Match trace at one side to avoid reflections bouncing back and forth.

Decoupling and Power Supply Considerations

- Place decoupling capacitors as close as possible to the VDD pin(s) to limit noise from the power supply
- Addition of a ferrite bead in series with VDD can help prevent noise from other board sources
- Value of decoupling capacitor is frequency dependant. Typical values to use are 0.1 μF for designs using frequencies < 50MHz and 0.01 μF for designs using frequencies > 50MHz.

Typical CMOS termination

Place Series Resistor as close as possible to CMOS output

CMOS Output Buffer To CMOS Input (Typical buffer impedance 20 Ω) 50Ω line Connect a 33 Ω series resistor at each of the output clocks to enhance the

stability of the output signal



ABSOLUTE MAXIMUM CONDITIONS

Supply Voltage to Ground Potential-0.5V to 4.6V DC Input Voltage V_{SS} - 0.5V to 4.6V Storage Temperature-65°C to 150°C

Junction Temperature 150°C Static Discharge Voltage (per MIL-STD-883, Method 3015).....> 2000V

OPERATING CONDITIONS

Description	Parameter	Min	Max	Unit
Supply Voltage	V _{DD}	2.25	3.63	V
Load Capacitance, <100 MHz, 3.3V	C _L ^[4]	_	30	pF
Load Capacitance, <100 MHz, 2.5V with High Drive		_	30	pF
Load Capacitance, <133.3 MHz, 3.3V		_	22	pF
Load Capacitance, <133.3 MHz, 2.5V with High Drive		_	22	pF
Load Capacitance, <133.3 MHz, 2.5V with Standard Drive		_	15	pF
Load Capacitance, >133.3 MHz, 3.3V		_	15	pF
Load Capacitance, >133.3 MHz, 2.5V with High Drive		-	15	pF
Input Capacitance ^[5]	CIN	-	5	pF
Closed-loop bandwidth (typical), 3.3V	BW	1		MHz
Closed-loop bandwidth (typical), 2.5V		0	.5	MHz
Output Impedance (typical), 3.3V High Drive	Rout	23		Ω
Output Impedance (typical), 3.3V Standard Drive		33		Ω
Output Impedance (typical), 2.5V High Drive		2	.6	Ω
Output Impedance (typical), 2.5V Standard Drive		3	9	Ω
Power-up time for all V_{DD} 's to reach minimum specified voltage (power ramps must be monotonic)	t _{PU}	0.01	250	ms

Notes:

4. Applies to Test Circuit #1.

5. Applies to both REF Clock and internal feedback path on CLKOUT.

6. Theta Ja, EIA JEDEC 51 test board conditions, 2S2P; Theta Jc Mil-Spec 883E Method 1012.1.



3.3V DC ELECTRICAL SPECIFICATIONS

Description	Parameter	Test Conditions	Min	Max	Unit
Supply Voltage	V_{DD}		2.97	3.63	V
Input LOW Voltage	VL		-	0.8	V
Input HIGH Voltage	V _{IH}		2.5	V _{DD} + 0.3	V
Input Leakage Current	IL	$0 < V_{IN} < V_{IL}$	-	±10	μA
Input HIGH Current	I _{IH}	V _{IN} = V _{DD}	-	100	μA
Output LOW Voltage	V _{OL}	I_{OL} = 8 mA (Standard Drive) I_{OL} = 12 mA (High Drive)		0.4 0.4	V V
Output HIGH Voltage	V _{он}	I_{OH} = -8 mA (Standard Drive) I_{OH} = -12 mA (High Drive)	2.4 2.4		V V
Supply Current	I _{DD}	Unloaded outputs, 66-MHz REF	-	45	mA

2.5V DC ELECTRICAL SPECIFICATIONS

Description	Parameter	Test Conditions	Min	Max	Unit
Supply Voltage	V _{DD}		2.25	2.75	V
Input LOW Voltage	VIL		-	0.7	V
Input HIGH Voltage	V _{IH}		1.7	V _{DD} + 0.3	V
Input Leakage Current	IL	0 <v<sub>IN < V_{IL}</v<sub>	-	±10	μA
Input HIGH Current	I _{IH}	V _{IN} = V _{DD}	_	100	μA
Output LOW Voltage	V _{OL}	I_{OL} = 8 mA (Standard Drive) I_{OL} = 12 mA (High Drive)		0.5 0.5	V
Output HIGH Voltage	V _{он}	I_{OH} = -8 mA (Standard Drive) I_{OH} = -12 mA (High Drive)	$V_{DD} - 0.6$ $V_{DD} - 0.6$		V
Supply Current	I _{DD}	Unloaded outputs, 66-MHz REF	-	30	mA



3.3V AND 2.5V AC ELECTRICAL SPECIFICATIONS

Description Parameter Test Conditions		Test Conditions	Min	Тур	Max	Unit
		3.3V High Drive	10	I	220	MHz
Maximum Frequency ^[7]	4 /4	3.3V Standard Drive		-	167	MHz
(Input/Output)	1/t1	2.5V High Drive	10	-	200	MHz
		2.5V Standard Drive	10	-	134	MHz
Input Duty Cycle	Ŧ	<133.3 MHz	25	-	75	%
(PLL Mode only)	TIDC	>133.3 MHz	40	-	60	%
Output Duty Ougla ^[8]	4 . 4	<133.3 MHz	47	-	53	%
Output Duty Cycle ^[8]	$t_2 \div t_1$	>133.3 MHz	45	I	55	%
		Standard Drive, CL = 30 pF, <100 MHz	_	1.6	-	ns
		Standard Drive, CL = 22 pF, <133.3 MHz	_	1.6	-	ns
		Standard Drive, CL = 15 pF, <167 MHz	_	0.6	-	ns
Rise, Fall Time (3.3V) ^[8]	t3,t4	High Drive, CL = 30 pF, <100 MHz	_	1.2	-	ns
		High Drive, CL = 22 pF, <133.3 MHz		1.2	-	ns
		High Drive, CL = 15 pF, >133.3 MHz	-	0.5	-	ns
	t ₃ , t ₄	Standard Drive, CL = 15 pF, <133.33 MHz		1.5	_	ns
		High Drive, CL = 30 pF, <100 MHz	-	2.1	-	ns
Rise, Fall Time (2.5V) ^[8]		High Drive, CL = 22 pF, <133.3 MHz	-	1.3	-	ns
		High Drive, CL = 15 pF, >133.3 MHz	_	1.2	_	ns
Output to Output Skew [8]	t ₅	All outputs equally loaded	_	-	100	ps
Delay, REF Rising Edge] t ₆	PLL enabled @ 3.3V		I	100	ps
to CLKOUT Rising Edge ^[8]		PLL enabled @2.5V	-200	I	200	ps
	4	Measured at $V_{DD}/2$. Any output to any output, 3.3V supply	_	_	±150	ps
Part to Part Skew ^[8]	t ₇	Measured at $V_{DD}/2$. Any output to any output, 2.5V supply	_	-	±300	ps
PLL Lock Time ^[8]	t _{LOCK}	Stable power supply, valid clocks pre- sented on REF and CLKOUT pins	_	-	1.0	ms
		3.3V, >66 MHz, <15 pF		Ι	55	ps
		3.3V, >66 MHz, <30 pF, Standard. Drive		-	125	ps
Cycle-to-Cycle Jitter,	–	3.3V, >66 MHz, <30 pF, High Drive		_	100	ps
Peak ^[8, 9]	TJCC	2.5V, >66 MHz, <15 pF, Standard. Drive	_	_	95	ps
		2.5V, >66 MHz, <15 pF, High Drive	_	-	65	ps
		2.5V, >66 MHz, <30 pF, High Drive	_	_	145	ps

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3.3V AND 2.5V AC ELECTRICAL SPECIFICATIONS (continued)

Description	Parameter	Test Conditions	Min	Тур	Max	Unit
		3.3V, 66–100 MHz, <15 pF	-	-	75	ps
		3.3V, >100 MHz, <15 pF	-	-	45	ps
		3.3V, >66 MHz, <30 pF, Standard Drive	-	-	100	ps
Period Jitter, Peak ^[8,9]	T _{PER}	3.3V, >66 MHz, <30 pF, High Drive	-	-	70	ps
		2.5V, >66 MHz, <15 pF, Standard. Drive	-	-	60	ps
		2.5V, 66–100 MHz, <15 pF, High Drive	-	-	60	ps
		2.5V, >100 MHz, <15 pF, High Drive	-	-	45	ps

Notes:

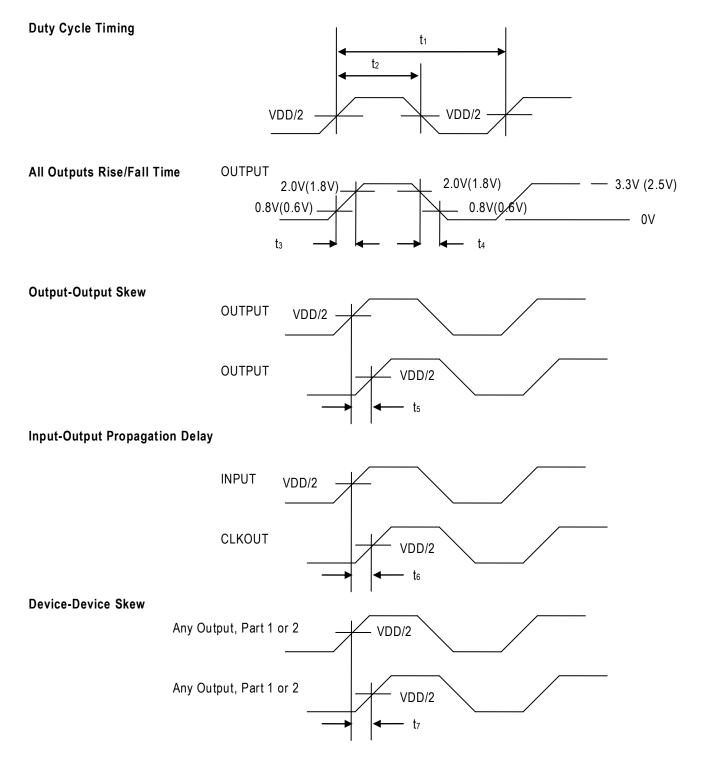
- 7. For the given maximum loading conditions. See C_L in Operating Conditions Table.
- 8. Parameter is guaranteed by design and characterization. Not 100% tested in production.
- 9. Typical jitter is measured at 3.3V or 2.5V, 29°C, with all outputs driven into the maximum specified load.



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Low Skew Zero Delay Buffer

SWITCHING WAVEFORMS

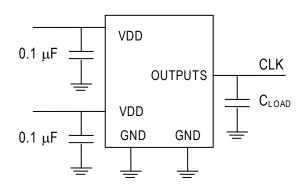


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TEST CIRCUITS

Test Circuit #1



PACKAGE DRAWINGS (GREEN PACKAGE COMPLIANT)

16 PI	N Narrow	SOP, TSS	OP (mm)	
	SC)P	TSS	OP	Е н
Symbol	Min.	Max.	Min.	Max.	
Α	1.35	1.75	-	1.20	
A1	0.10	0.25	0.05	0.15	
В	0.33	0.51	0.19	0.30	▲▶
С	0.19	0.25	0.09	0.20	
D	9.80	10.00	4.90	5.10	
E	3.80	4.00	4.30	4.50	
Н	5.80	6.20	6.40	BSC	
L	0.40	1.27	0.45	0.75	
е	1.27	BSC	0.65	BSC	



ORDERING INFORMATION

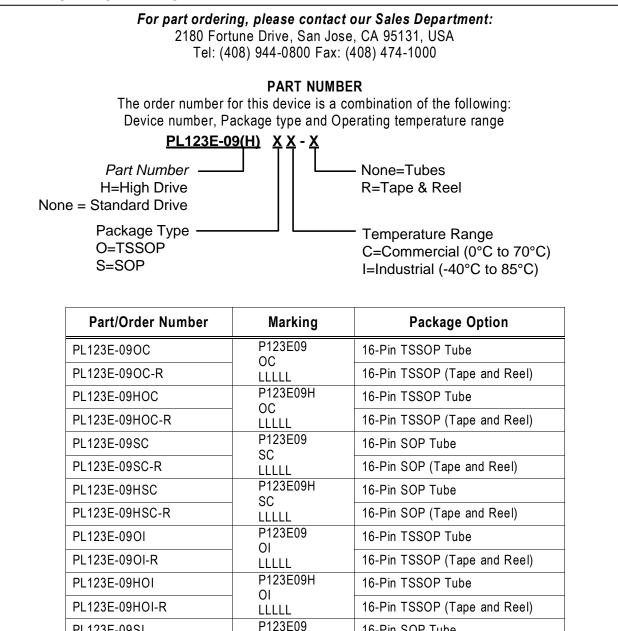
PL123E-09SI

PL123E-09SI-R

PL123E-09HSI

PL123E-09HSI-R

Note: LLLLL designates lot number



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16-Pin SOP Tube

16-Pin SOP Tube

16-Pin SOP (Tape and Reel)

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written approval of the President of Micrel Inc.

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